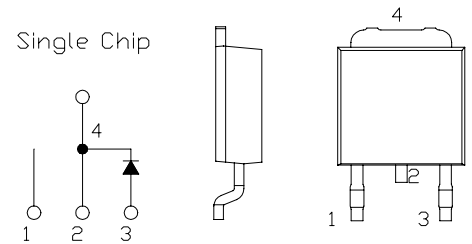


SBD Type : ESL03B03-F

OUTLINE DRAWING

FEATURES

- * TO-252AA Case, Surface Mounting Device
- * Extremely Low Forward Voltage drop
- * Low Power Loss
- * High Surge Capability
- * Packaged in 16mm Tape and Reel



Maximum Ratings

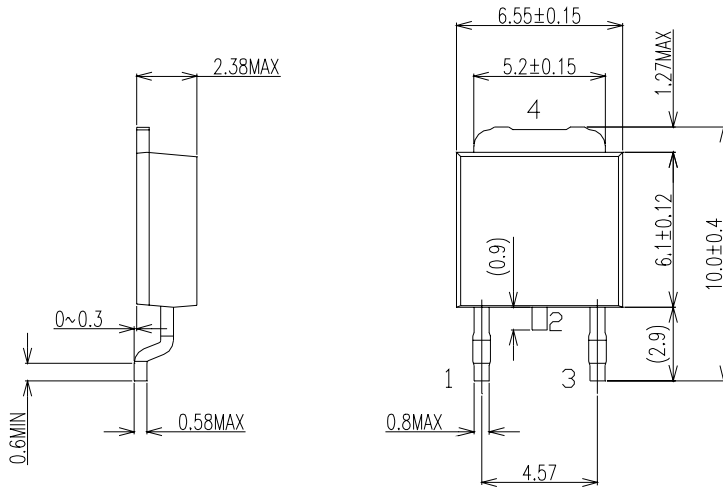
Approx Net Weight:0.30g

Rating	Symbol	ESL03B03-F			Unit
Repetitive Peak Reverse Voltage	V_{RRM}	30			V
Average Rectified Output Current	I_O	3.0	$T_c=82^\circ\text{C}$	50Hz Half Sine Wave Resistive Load	A
RMS Forward Current	$I_{F(RMS)}$	4.71			A
Surge Forward Current	I_{FSM}	45	50Hz Half Sine Wave, 1cycle, Non-repetitive		A
Operating Junction Temperature Range	T_{jw}	- 40 to + 100			$^\circ\text{C}$
Storage Temperature Range	T_{stg}	- 40 to + 125			$^\circ\text{C}$

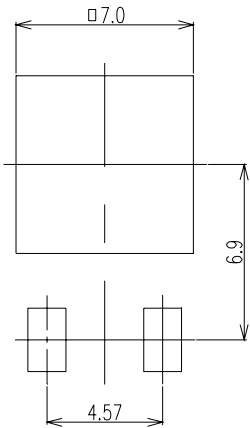
Electrical • Thermal Characteristics

Characteristics	Symbol	Conditions	Min	Typ	Max	Unit
Peak Reverse Current	I_{RM}	$T_j=25^\circ\text{C}, V_{RM}=V_{RRM}$	-	-	3.0	mA
Peak Forward Voltage	V_{FM}	$T_j=25^\circ\text{C}, I_{FM}= 3 \text{ A}$	-	-	0.47	V
Thermal Resistance Junction to Case	$R_{th(j-c)}$	-	-	-	6	$^\circ\text{C/W}$

ESL03B03-F OUTLINE DRAWING (Dimensions in mm)



SOLDERING PAD



Single Chip

